

# Single P-Channel 20 V (D-S) MOSFET With Schottky Diode

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)				
- 20	0.048 at V <sub>GS</sub> = - 4.5 V	- 6.3				
	0.068 at V <sub>GS</sub> = - 2.5 V	- 5.3				
	0.090 at V <sub>GS</sub> = - 1.8 V	- 4.6				

SCHOTTKY PRODUCT SUMMARY					
V <sub>KA</sub> (V)	V <sub>f</sub> (V) Diode Forward Voltage	I <sub>F</sub> (A)			
20	0.48 V at 0.5 A	1			

PowerPAK 1212-8

#### **FEATURES**

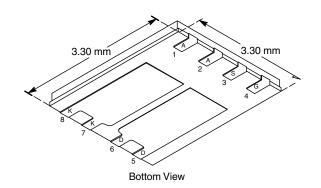
- TrenchFET® Power MOSFETS: 1.8 V Rated
- ESD Protected: 4500 V
- Ultra-Low Thermal Resistance, PowerPAK® Package with Low 1.07 mm Profile
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912

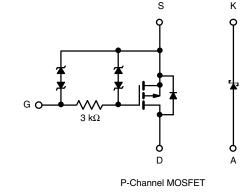


COMPLIANT HALOGEN **FREE** 

#### **APPLICATIONS**

· Charger Switching





#### Ordering Information:

Si7703EDN-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter		Symbol	10 s	Steady State	Unit	
Drain-Source Voltage (MOSFET and Schottky)		$V_{DS}$	- 20			
Reverse Voltage (Schottky)		$V_{KA}$	20		V	
Gate-Source Voltage (MOSFET)		$V_{GS}$	± 12	± 12		
Continuous Drain Current (T, I = 150 °C) (MOSFE	T <sub>A</sub> = 25 °C	I <sub>D</sub>	- 6.3	- 4.3		
Continuous Dialii Curient (1,j = 150 C) (MOSFE	$T_A = 85 ^{\circ}C$	- 'b	- 4.5	- 3.1		
Pulsed Drain Current (MOSFET)		I <sub>DM</sub>	- 20		Α	
Continuous Source Current (MOSFET Diode Conduction) <sup>a</sup>		I <sub>S</sub>	- 2.3	- 1.1	А	
Average Foward Current (Schottky)		Ι <sub>Ε</sub>	1			
Pulsed Foward Current (Schottky)		I <sub>FM</sub>	7			
Maximum Barray Dissipation (MOCFET)	T <sub>A</sub> = 25 °C		2.8	1.3	W	
Maximum Power Dissipation (MOSFET) <sup>a</sup>	$T_A = 85  ^{\circ}C$	P <sub>D</sub>	1.5	0.7		
Maximum Power Dissipation (Schottky) <sup>a</sup>	T <sub>A</sub> = 25 °C	ט י	2	1.1	VV	
	T <sub>A</sub> = 85 °C		1	0.6		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150 260		°C	
Soldering Recommendations <sup>b,c</sup>						

#### Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. See solder profile (www.vishav.com/doc?73257). The PowerPAK 1212-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- c. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.

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THERMAL RESISTANCE RATINGS							
Parameter		Device	Symbol	Typical	Maximum	Unit	
Junction-to-Ambient <sup>a</sup>	t ≤ 10 s	MOSFET	R <sub>thJA</sub>	35	44	°C/W	
		Schottky		51	64		
	Steady State	MOSFET		<sup>1</sup> thJA 75 94	94		
		Schottky		91	115		
Junction-to-Case (Drain)	Steady State	MOSFET	R <sub>thJC</sub>	4	5		
		Schottky		10	12		

#### Notes

a. Surface Mounted on 1" x 1" FR4 board.

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit		
Static								
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = -800 \mu A$	- 0.45		- 1	V		
Cata Dady Laglage		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 4.5 \text{ V}$			± 1.5	μΑ		
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	mA		
Zava Cata Valtaga Drain Current	1	V <sub>DS</sub> = - 20 V, V <sub>GS</sub> = 0 V	- 1		- 1			
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 85 ^{\circ}\text{C}$			- 5	μΑ		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 20			Α		
	R <sub>DS(on)</sub>	$V_{GS} = -4.5 \text{ V}, I_D = -6.3 \text{ A}$		0.041	0.048	Ω		
Drain-Source On-State Resistance <sup>a</sup>		$V_{GS} = -2.5 \text{ V}, I_D = -5.3 \text{ A}$		0.057	0.068			
		V <sub>GS</sub> = - 1.8 V, I <sub>D</sub> = - 1 A		0.072	0.090			
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = - 10 V, I <sub>D</sub> = - 6.3 A		14		S		
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	I <sub>S</sub> = - 2.3 A, V <sub>GS</sub> = 0 V		- 0.8	- 1.2	٧		
Dynamic <sup>b</sup>								
Total Gate Charge	$Q_g$			12	18			
Gate-Source Charge	$Q_{gs}$	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -6.3 \text{ A}$		2.5		nC		
Gate-Drain Charge	$Q_{gd}$			2.9		1		
Turn-On Delay Time	t <sub>d(on)</sub>			2.5	4			
Rise Time	t <sub>r</sub>	$V_{DD}$ = - 10 V, $R_L$ = 10 $\Omega$		4	6			
Turn-Off DelayTime	t <sub>d(off)</sub>	$\text{I}_\text{D}\cong$ - 1 A, $\text{V}_\text{GEN}$ = - 4.5 V, $\text{R}_\text{G}$ = 6 $\Omega$		15	23	νs		
Fall Time	t <sub>f</sub>			12	18	ì		

#### Notes

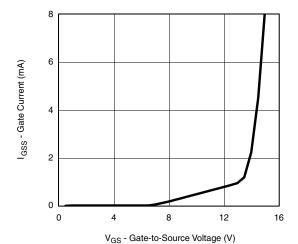
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

SCHOTTKY SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted)							
Parameter	Symbol	Test Conditions	Тур.	Max.	Unit		
Forward Voltage Drop	V <sub>F</sub>	$I_{F} = 0.5 \text{ A}$		0.42	0.48	V	
		I <sub>F</sub> = 0.5 A, T <sub>J</sub> = 125 °C		0.33	0.4	, v	
Maximum Reverse Leakage Current	I <sub>rm</sub>	V <sub>r</sub> = 20 V		0.002	0.100		
		V <sub>r</sub> = 20 V, T <sub>J</sub> = 85 °C		0.10	1	mA	
		V <sub>r</sub> = 20 V, T <sub>J</sub> = 125 °C		1.5	10		
Junction Capacitance	C <sub>T</sub>	V <sub>r</sub> = 10 V		31		pF	

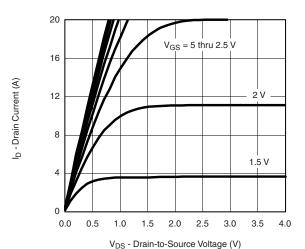
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



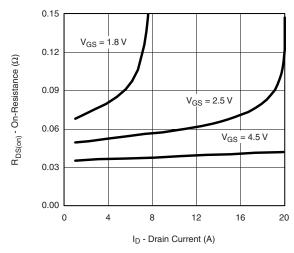
## **MOSFET TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



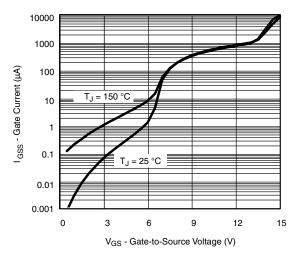
#### Gate-Current vs. Gate-Source Voltage



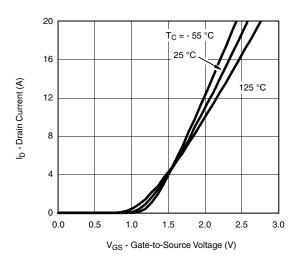
## **Output Characteristics**



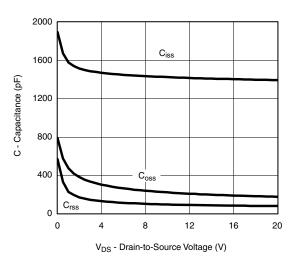
On-Resistance vs. Drain Current



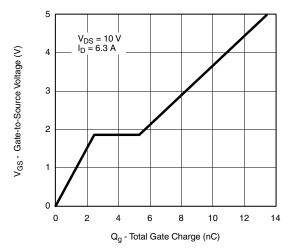
Gate Current vs. Gate-Source Voltage



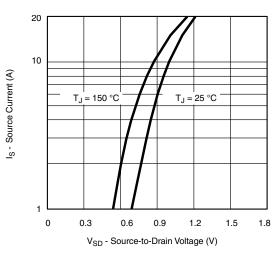
Transfer Characteristics



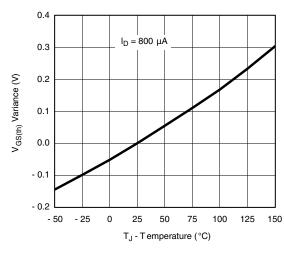
## **MOSFET TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



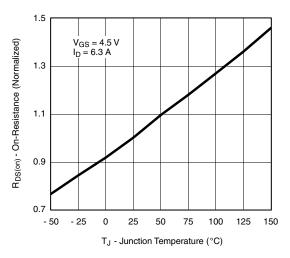
### **Gate Charge**



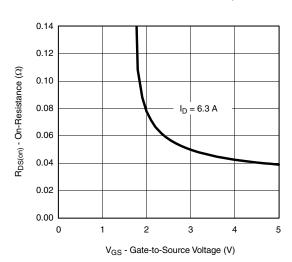
## Source-Drain Diode Forward Voltage



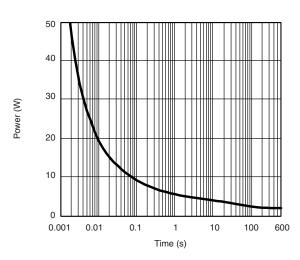
**Threshold Voltage** 



On-Resistance vs. Junction Temperature



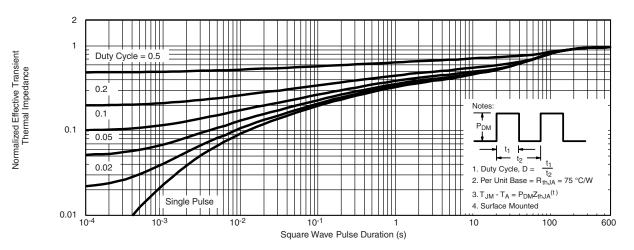
On-Resistance vs. Gate-to-Source Voltage



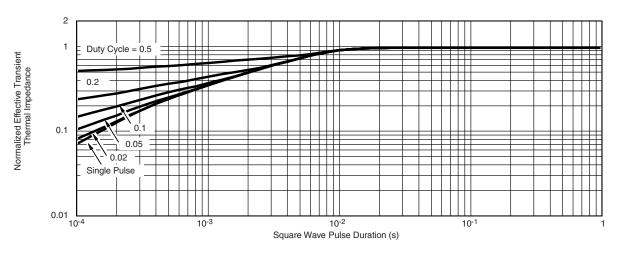
Single Pulse Power, Junction-to-Ambient



## **MOSFET TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)

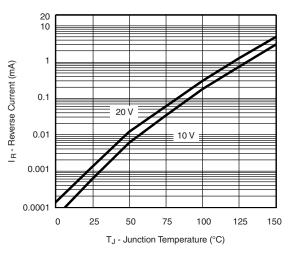


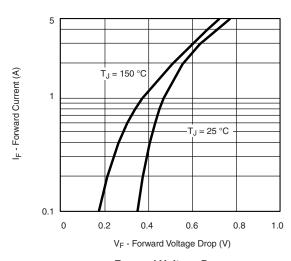
Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

## **SCHOTTKY TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



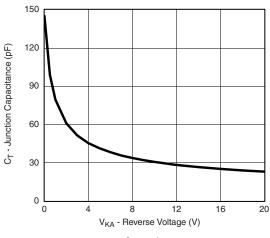


**Reverse Current vs. Junction Temperature** 

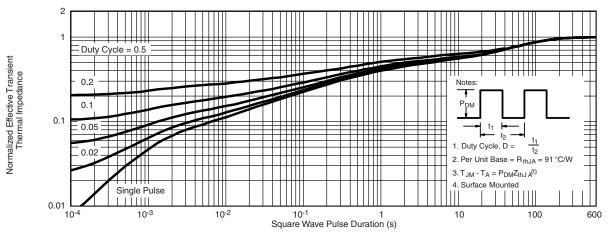
**Forward Voltage Drop** 



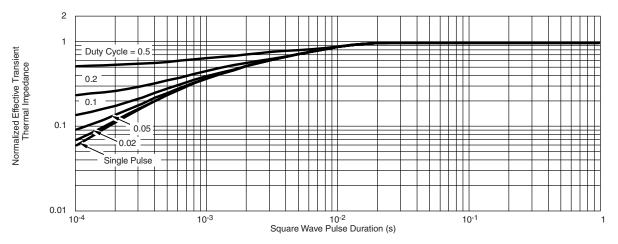
## SCHOTTKY TYPICAL CHARACTERISTICS ( $T_A = 25$ °C, unless otherwise noted)



#### Capacitance



## Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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